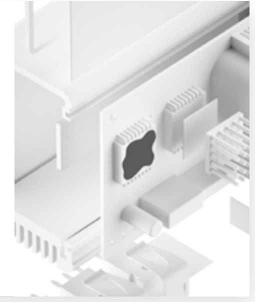
# SILICONE GAP FILLER / PUTTY TGL-W-SI

dispensable

HALA

TGL-W-SI is an electrically insulating thermally conductive, highly viscous dispensable form-in-place gap filler. It is ideal for use in applications where thermal transfer over large gaps caused e.g. by big tolerances or different stack up heights must be achieved. The ready-made compound does not require an additional crosslinking process. Due to the specific formulation and filling with ceramic particles the material has a very high thermal conductivity. After dispensing the viscoplastic material leads to an optimum thermal contact at no pressure. By its use the total thermal resistance is minimised.



Release 01 / 2024
Technical Data Sheet

## PROPERTIESEN

- Dispensable
- Almost zero pressure at assembly due to viscoplasticity
- Thermal conductivity: 3.3 [1] / 5.5 [2] W/mK
- Ready-made, no additional crosslinking required

## AVAILABILITY

- Cartridge 30 ml
- Pail 2 kg
- Others on request

## APPLICATION EXAMPLES

Thermal link of:

- SMD packages
- Through-hole vias
- RDRAMs memory modules
- Flip Chips, DSPs, BGAs, PPGAs

For use in Automotive applications / Laptops / Medicine engineering / Industrial PCs

| PROPERTY | UNIT | TGL-W-SI |
|---|---|---|
| **MATERIAL** | | Ceramic filled silicone compound |
| Colour | | Grey |
| Density | g/cm³ | 3.1 |
| Viscosity (@ 10 ¹/min, 25 °C) | Pas | 500 |
| Penetration | mm/10 | 290 |
| RoHS Conformity | 2015 / 863 / EU | Yes |
| **THERMAL** | | |
| Thermal Conductivity [1] | W/mK | 3.3 |
| Thermal Conductivity [2] | W/mK | 5.5 |
| Operating Temperature Range | °C | - 40 to + 130 |
| **ELECTRICAL** | | |
| Dielectric Strength | kV / mm | 7 |
| Volume Resistance | Ohm - cm | $1.1 \times 10^{14}$ |

Test Methods: [1]ASTM D 5470. [2] Intern method. All data without warranty and subject to change. Please contact us for further data and information.

All technical data and information are without warranty and believed to be reliable and accurate corresponding to the latest state of the art. Since the products are not provided to conform with mutually agreed specifications and their use and processing are unknown we cannot guarantee results, freedom from patent infringement, or their suitability for any application. Product testing by the applicant is recommended. We reserve the right of changes.

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